

NOTES :

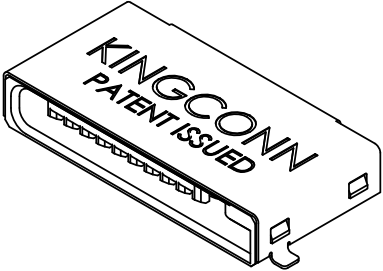
- MATERIAL :
INSULATOR : LCP UL 94V-0
CONTACT : COPPER ALLOY
- APPLICATION:
MS & MS Duo & MS PRO & MS PRO Duo & MagicGate MS Duo & MS I/O Expansion & MS-ROM & MS Duo-ROM & MagicGate MS
- PART NO : 7MSMS-~~X~~ X- X111

PACKING:
0:TRAY
1:CARRIER

COLOR:
0:BLACK
9:IVORY

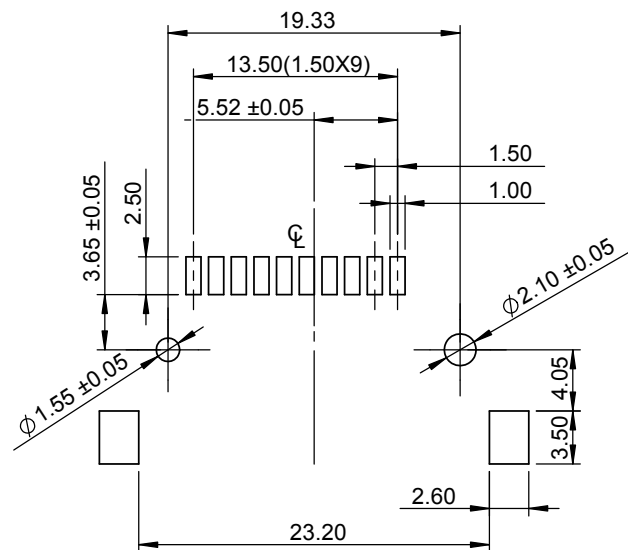
PLATING:
F: CONTACT AREA:GLOD FLASH Au PLATED OVER Ni
SOLDER AREA: MATTE Tin PLATED OVER Ni
B: CONTACT AREA:10μ" Au PLATED OVER Ni
SOLDER AREA: MATTE Tin PLATED OVER Ni

更改 REV	設 變 內 容 MODIFICATION
F	ECN00868
G	ECN01167
H	ECN02759
I	ECN03144
J	ECN03179

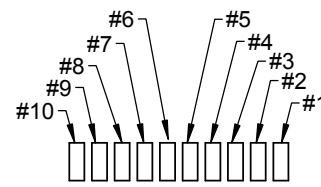


GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X±0.50	X°±5°	名 稱(TITLE) Memory Stick & Memory Stick Duo CONNECTOR REVERSE TYPE	
.X±0.30	.X°±2°		
.XX±0.20	.XX°±1°		
單 位(UNIT) mm	料 號(PART NO.) 7MSMS-XX-X111	圖 號(DWG NO.) 7MSMS-XX-X111-J	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 2:1
			張 數 SHEET 1/2
			角 法 PROJ
			更 改 REV J

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F	ECN00868
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RECOMMEND PCB LAYOUT



PIN DEFINITION

MS#1	VSS
MS#2	BS
MS#3	DATA1
MS#4	SDIO/DATA0
MS#5	DATA2
MS#6	INS
MS#7	DATA3
MS#8	SCLK
MS#9	VCC
MS#10	VSS

GROUND PAD X 2

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X ± 0.50	X ° ± 5 °		
.X ± 0.30	.X ° ± 2 °		
.XX ± 0.20	.XX ° ± 1 °		
單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)	
mm	7MSMS-XX-X111	7MSMS-XX-X111-J	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 2:1
			張 數 SHEET 2/2
			角 法 PROJ 更改 REV J

